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(12) **United States Design Patent**
Hu

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(54) **PRINTED CIRCUIT BOARD OF SOLID-STATE MEMORY**

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(**) Term: **14 Years**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 174/68.1, 250, 256, 257; 318/567, 568.1; 700/22; 361/720, 722, 361/748, 749, 750, 751, 757, 752, 761, 762, 361/763, 764
See application file for complete search history.

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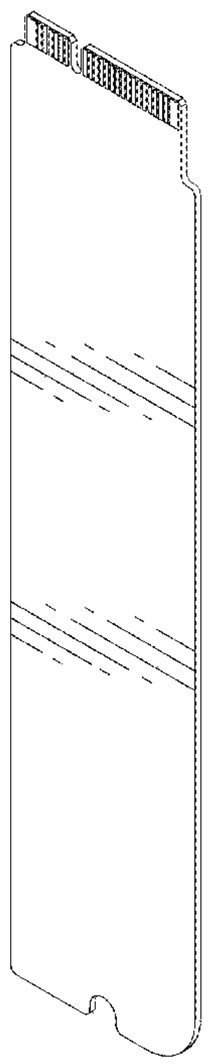
(57) **CLAIM**

The ornamental design for a printed circuit board of solid-state memory, as shown and described.

DESCRIPTION

FIG. **1** is a front, right, top perspective view of a printed circuit board of solid-state memory showing my new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top view thereof; and,
FIG. **7** is a bottom view thereof.

1 Claim, 7 Drawing Sheets



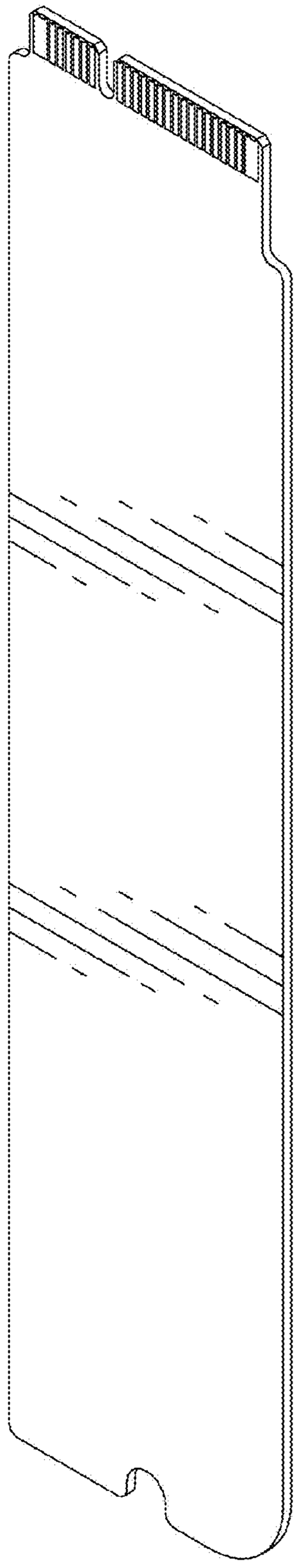


FIG. 1

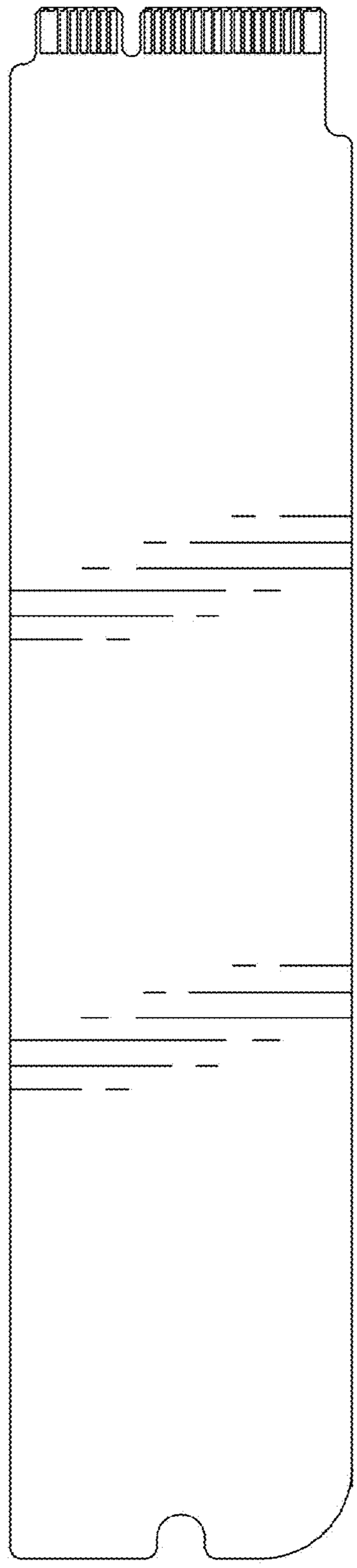


FIG. 2

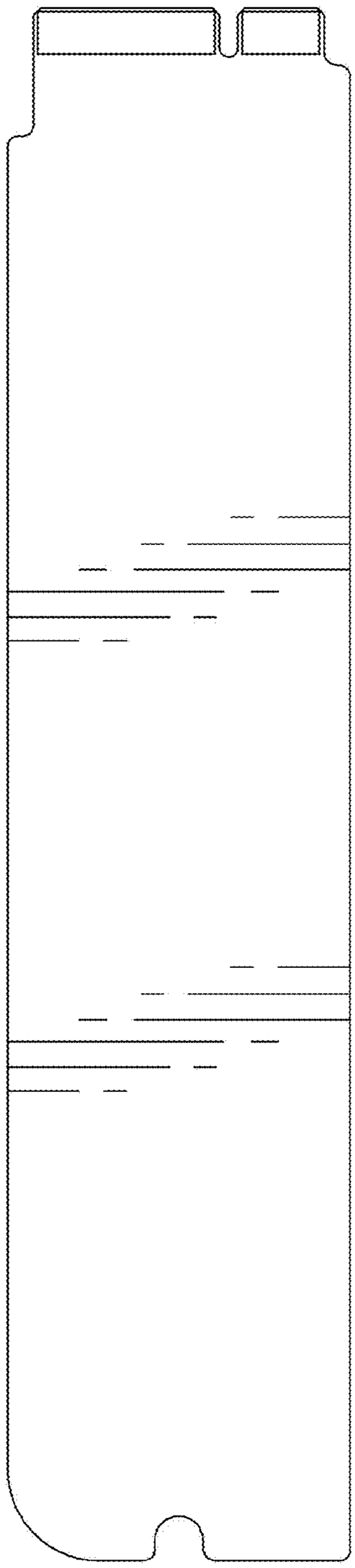


FIG. 3

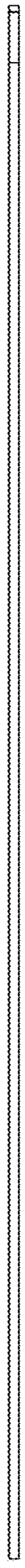


FIG. 4

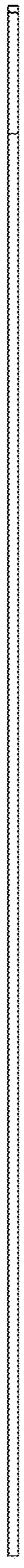


FIG. 5

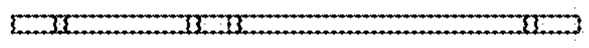


FIG. 6

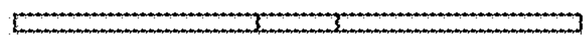


FIG. 7